Service Repair Documentation
Level 3 (level 2,5e)
M315 / AP75

Release	Date	Department	Notes to change
R 1.0	12.12.2005	BenQ Mobile (Taipei/KLF)	New document
R 1.1	02.03.2006	BenQ Mobile (KLF)	Level changed

Table of Content

1 Introduction

1.1 Purpose

This Service Repair Documentation is intended to carry out repairs on BenQ repair level 3-4.

1.2 Scope

This document is the reference document for all BenQ authorised Service Partners which are released to repair Siemens mobile phones up to level 2.5.

1.3 Terms and Abbreviations

2 List of available level 4 (level 2,5e) parts

(According to Component Matrix V1.xx - check C-market for updates)

Product	ID	Order Number	Description CM
M315		L50-D104-D670	DISDIODE HVC358B 15V BQ83.00358.010
M315		L50-D5106-D670	DISDIODE RB520S-30 BQ83.00520.080
M315		L50-D5108-D670	DISDIODE CRS03 30V1A BQ83.1R003.A8Q
M315		L50-D3139-D670	DISDIODE ZEN 6.06-6.33V BQ83.6R205.03F
M315		L50-C2123-D670	DISTRANS PEMH9 NPN SOT666 BQ84.00009.010
M315		L50-C2124-D670	DISTRANS NSBC144EDXV6T1 BQ84.00144.020
M315		L50-C2125-D670	DISTRANS BC807-40W BQ84.00807.A1K
M315		L50-C2126-D670	DISTRANS UMT4403 UMT3 BQ84.04403.01F
M315		L50-C1153-D670	DISTRANS FDC6506P SOT-6 BQ84.06506.030
M315		L50-C2127-D670	DISTRANS DTC143ZET1 SC-75 BQ84.0C143.01P
M315		L50-K280-Y410	FILTER SAW B9020 1960MHZ BQ69.10078.051
M315		L50-K280-Y411	FILTER SAW B9017 942,5MHZ BQ69.10100.051
M315		L50-K280-Y412	FILTERSAW LL37D 1842,5MHZ BQ69.10112.041
M315		L50-U6092-D670	FILEMI 800-2700MHZ CSP204 BQ69.10159.001
M315		L50-U6093-D670	FILEMI 1GHZ CSPEMI202A BQ69.10160.001
M315		L50-K280-Y413	FILTER LFB212G45 2,45GHZ BQ69.10168.011
M315		L50-K280-Y414	FILTER-A NFA21SL287V1A48L BQ69.12003.001
M315		L50-F4103-J4	RES NTC 0402 10K NTH5G BQ69.60009.001
M315		L50-D105-D670	DISDIODE TVS6.5V170P 0402 BQ69.80009.011
M315		L50-F2110-M	VARISTOR 11V TVM1A150LBR BQ69.80011.021
M315		L50-Z1901-A63	ANT 2.4GHz AT5020-B2R8HAA BQ69.F0005.021
M315		L50-D106-D670	DISDIODE TVS 5V 39P 0402 BQ6J.80050.001
M315		L50-D107-D670	DISDIODE TVS 5V 470P 0402 BQ6J.80050.011
M315		L50-G6251-D670	IC CTRL SPCA550A TFBGA80 BQ71.00550.A0U
M315		L50-L6184-D670	IC MELODY YMU759B QFN32 BQ71.00759.005
M315		L50-G6252-D670	IC ABB TWL3014GGM PBGA100 BQ71.03014.00U
M315		L50-G6253-D670	IC BLUE CORE BC313143A13 BQ71.31314.00U
M315		L50-U6233-D670	IC ASIC D751749GHH BGA179 BQ71.75174.00U
M315		L50-F6448-D670	IC FLASH RD38F2030W0ZBQ1 BQ72.38203.A0T
M315		L50-B6212-D670	IC LOGIC MC74VHC1G32DFT1 BQ73.74132.0ZH
M315		L50-C6259-D670	IC LDO NCP561SN25T1 TSOP5 BQ74.00561.A3V
M315		L50-C6260-D670	IC RGL MIC2287-15BML MLF8 BQ74.02287.03F
M315		L50-C6261-D670	IC LDO AAT3218IGV-1.8-T1 BQ74.03218.03B
M315		L50-K280-Y416	SWITCHPLEXER LMSP54CA-272 BQ74.054CA.D30
M315		L50-C6262-D670	IC LDO MAS9124AST2-T BQ74.09124.03B
M315		L50-L6185-D670	IC XCVR HD155155NP QFN48P BQ74.15515.0F5
M315		L50-Z2002-A104	IC MODUL PWR AMPSKY77325 BQ74.77325.0K0
M315		L50-B6213-D670	IC DUAL BUFFER NC7WZ16 BQ74.7WZ16.0MY
M315		L50-F5220-J	CAP ARRAY 22P50VJ0805 NPO BQ77.62203.0C1
M315		L50-C6126-D670	IC V-DETECTOR XC61CC4402N BQ7D.00061.BBY
M315		L50-F102-Y24	CRYST 32.768K12.5PF20PPM BQ82.30001.H71
M315		L50-F102-Y25	OSCCRYST 26MHZ 10PF 8PPM BQ82.30026.D01

Required Equipment for Level 4 (level 2,5e)

- GSM-Tester (CMU200 or 4400S incl. Options)
- PC-incl. Monitor, Keyboard and Mouse
- Adapter cable for Bootadapter (F30032-xx-A1)
- Troubleshooting Frame M315_AP75 (F30032-xx-A1)
- Power Supply
- Spectrum Analyser
- Active RF-Probe incl. Power Supply
- Oscilloscope incl. Probe
- RF-Connector (N<>SMA(f))
- Power Supply Cables
- Dongle (F30032-xx-A1)
- BGA Soldering equipment

Reference: Equipment recommendation V1.6
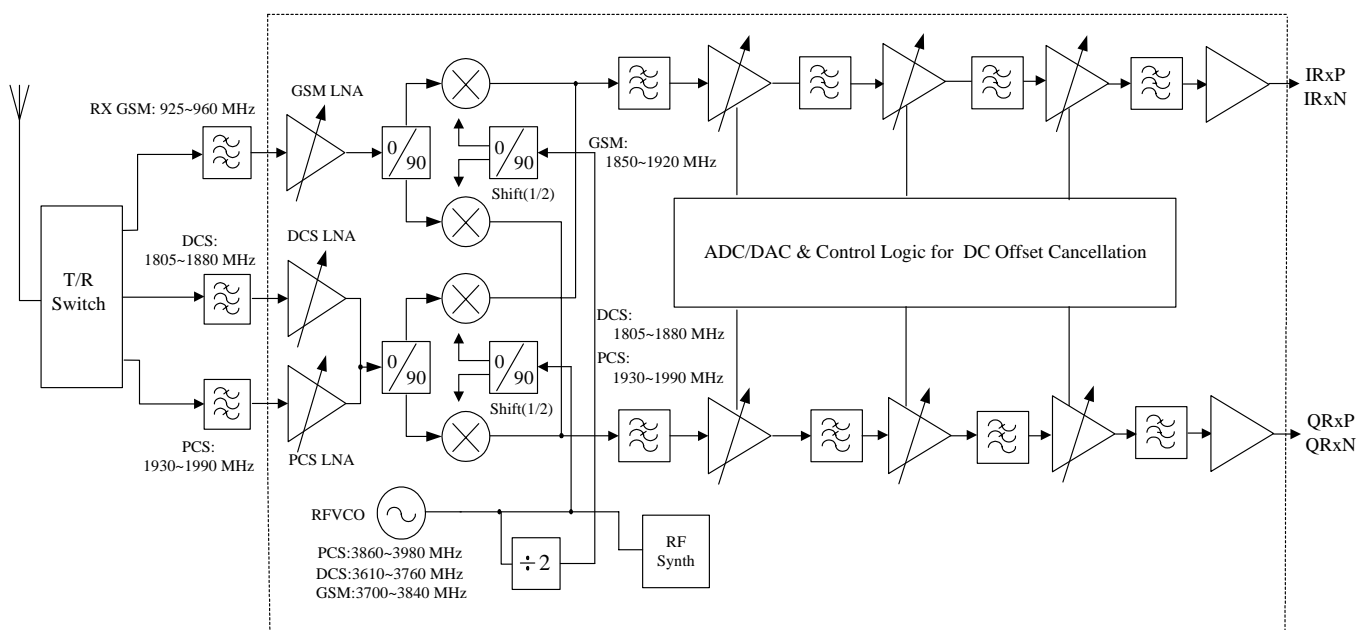(Downloadable from the technical support page)

3   Required Software for Level 4 (level 2,5e)

- Windows XP
- XCSD Tools Level 2
- GRT Version 3 or higher
- Internet unblocking solution (JPICS)

4 Radio Part

M315 / AP75 utilizes TI's chipsets (CALYPSO-Lite and IOTA) as base-band solution. Base-band is composed with two potions: Logic and Analog/Codec. CALYPSO-Lite is a GSM/GPRS digital base-band logic solution included microprocessor, DSP, and peripherals. IOTA is a combination of analog/codec solution and power management which contain base-band codec, voice-band codec, several voltage regulators and SIM level shifter etc. In addition, 56E22 integrates with other features such as LED backlight, color LCD display, DSC, vibration, melody tone and charging etc. The following sections will present the operation theory with circuitry and descriptions respectively.
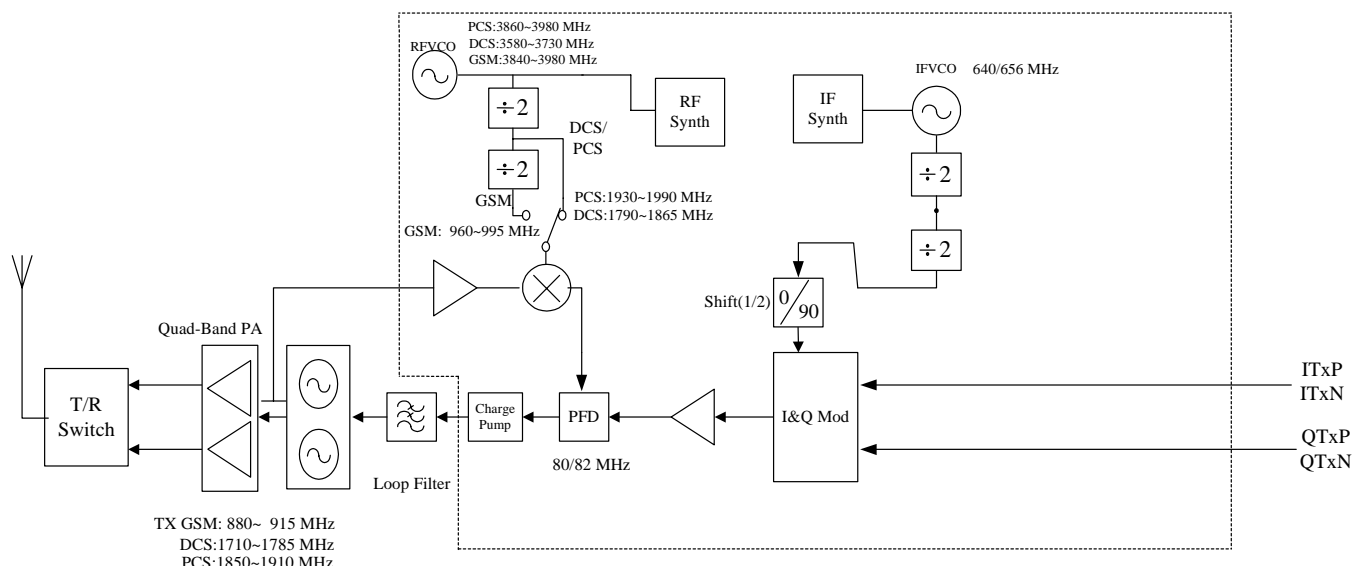
4.1 Receiver Operation

The Receiver structure in HD155155NP is a zero-IF solution. That means RF signal is directly down-converted to the baseband signal. And by the way, all of the DC-offset canceling processes are done within chip. We do not have to care about that.
The LNA amplifies the RF signal after passing the T/R switch and RF SAW filter and before it enters the down-converter section. The RF signal is mixed with a local oscillator (LO) signal to generate the baseband signal.
Three LPFs are used in the baseband signal processing for reducing blocking signals. The first LPF employs two external capacitors, and we can check whether the front-end (LNA + Mixer) is functionally well or not by probing these two capacitors to see if there is any baseband signal(<200kHz).
After three stages of DC-offset cancelling, the signal (I+/I-/Q+/Q-) then output to the baseband IC for further processing.
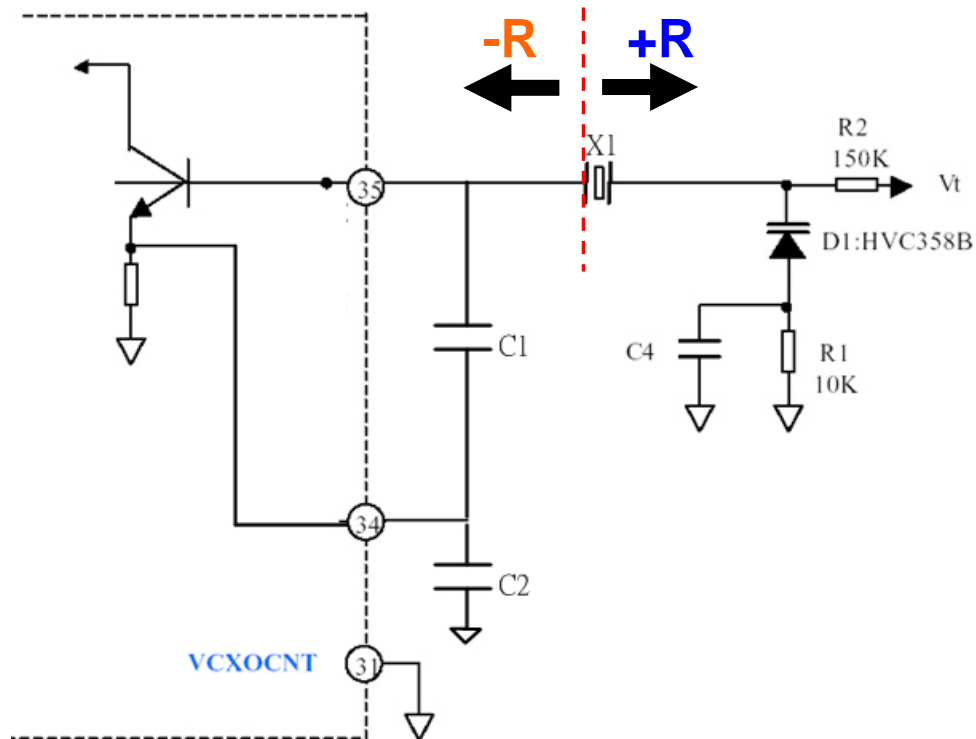
4.2 Transcriber Operation

The transmitter chain converts differential IQ baseband signals to a suitable format for transmission by a power amplifier.

The common mode voltage range of the modulator inputs is 1.05 V to 1.45 V and they have 2.0 Vpp differential swing. The modulator circuit uses double-balanced mixers for the I and Q paths. The Local signals are generated by dividing the IFLO signals by 8 in GSM band and by 4 in DCS band, and then passed to the modulator through a phase splitter / shifter. The IF signals generated are then summed to produce a single modulated IF signal which is amplified and fed into the offset PLL block.

Within the offset PLL block there are a down converter, a phase comparator and a VCO driver. The down converter mixes the first local signal and the TXVCO signal to create a reference local signal for use in the offset PLL circuit. The phase comparator and the VCO driver generate an error current, which is proportional to the phase differential between the reference IF and the modulated IF signals. This current is used in a third order loop filter to generate a voltage, which in turn modulates the TXVCO.

The RF signal is then amplified by PA and power control loop to the assigned power level within the burst ramping mask. After passing the LPF of the T/R switch, the signal is then radiated through the antenna.
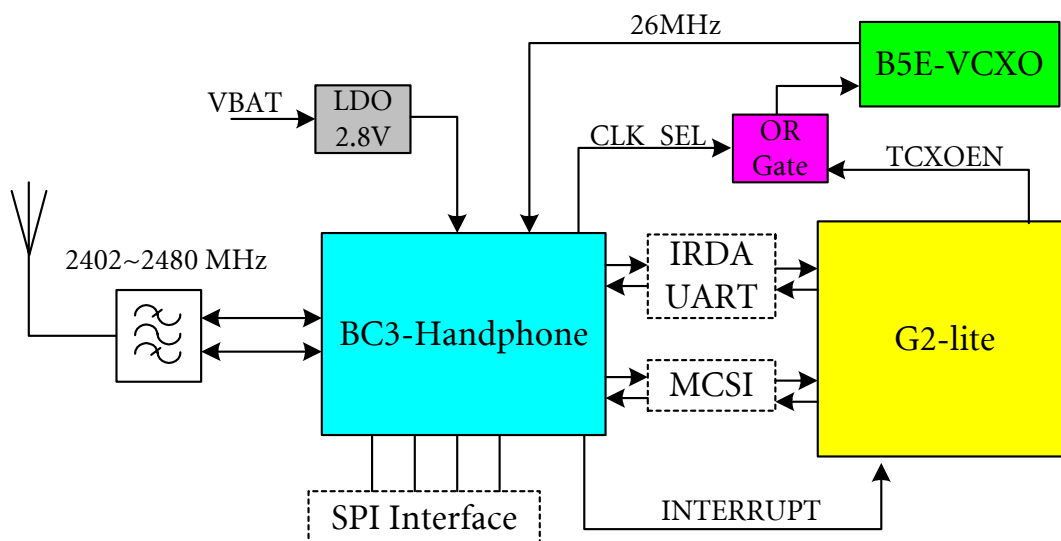
4.3 VCXO Operation

HD155155NP provides a VCXO function. With that function, we can build a reference clock generation circuits as shown in the above graph. This means that the VCTCXO module is not necessary for clock application, and only one crystal with 8ppm tolerance and one variocap are enough.

The transistor in HD155155NP and two internal capacitors (C1, C2) provide a negative resistance, and the crystal (X1) combined with some other passive components (including variocap r : D1) to provide a positive resistance. When these two resistance values equal to each other at some frequency, the oscillation will happen at that frequency. In our design target, the oscillation frequency should be within 26MHz +/-15 ppm.
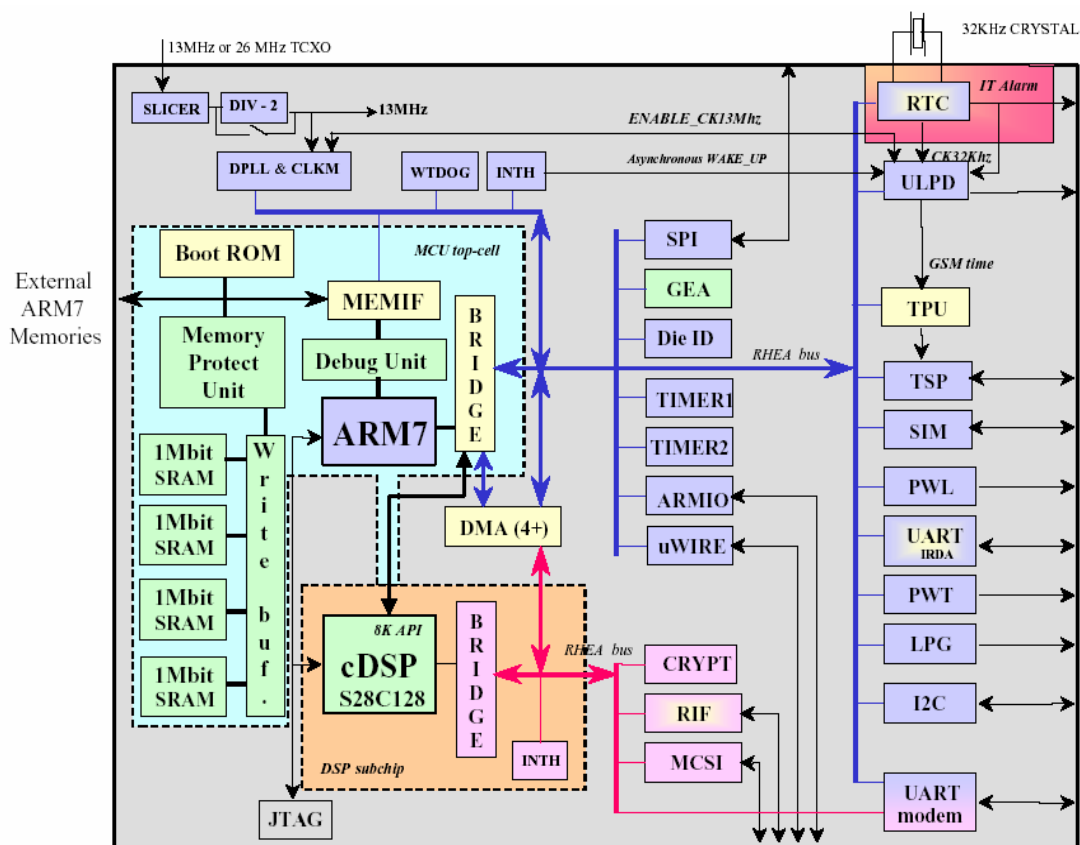
4.4 Bluetooth Operation

The Bluetooth main chip – BC3-Handphone deals with BT RF signal from chip antenna and baseband signal from G2-lite including down/up-converting, de/- modulation and de/- coding … The BC3-Handphone could accept clock frequency from 8MHz to 40MHz. In our application, we feed the chip with 26MHz clock from RF chip, HD155155N, and share with G2-lite by an OR-Gate. So GSM part and BT part could go to sleep respectively. BC3-Handphone could wake G2-lite up by a interrupt. The BC3-Handphone is controlled by AT commands that come from G2-lite via IRDA UART. The Data between BC3-Handphone and G2-lite are transmitted and received via MCSI interface. The SPI interface is reserved for firmware downloading for BT chip of Flash-type. The power BT chip needed outside is 2.8V the same with voltage level of I/O interface of G2-lite.

5 Logic (Base-Band)

Introduction:

56E22 utilizes TI's chipsets (CALYPSO-Lite and IOTA) as base-band solution. Base-band is composed with two potions: Logic and Analog/Codec. CALYPSO-Lite is a GSM/GPRS digital base-band logic solution included microprocessor, DSP, and peripherals. IOTA is a combination of analog/codec solution and power management which contain base-band codec, voice-band codec, several voltage regulators and SIM level shifter etc. In addition, 56E30 integrates with other features such as LED backlight, color LCD display , DSC, vibration, melody tone and charging etc. The following sections will present the operation theory with circuitry and descriptions respectively.

Block Diagram CPU CALYPSO (HERCROM40)

BenQ *mobile*

IOTA

5.1 Calypso-Lite

CALYPSO-Lite (HERCROM400) is a chip implementing the digital base-band processor of a GSM/GPRS mobile phone. This chip combines a DSP sub-chip (LEAD2 CPU) with its program and data memories, a Micro-Controller core with emulation facilities (ARM7TDMIE) and an internal 2M-bit RAM memory, a clock squarer cell, several compiled single-port or 2-ports RAM and CMOS gates.

Major functions of this chip are as follows:

Real Time Clock (RTC)
The RTC block is an embedded RTC module fed with an external 32.768KHz Crystal. Its basic functions are:
1. Time information (seconds/minutes/hours)
2. Calendar information (Day/Month/Year/ Day of the week) up to year 2099
3. Alarm function with interrupts (RTCINT is generated to wake up ABB)
4. 32KHz oscillator frequency gauging

Pulse Width Light (PWL)
This module allows the control of the backlight of LCD and keypad by employing a 4096 bit random sequence .In the 56E30, we use the LT/PWL function to turn on the keypad light LED.

MODEM-UART
This UART interface is compatible with the NS 16C750 device which is devoted to the connection to a MODEM through a standard wired interface. The module integrates two 64 words (9 and 11 bits) receive and transmit FIFOs which trigger levels are programmable. All modem operations are controllable either via a software interface or using hardware flow control signals. In 56E30 , we implement software flow control by only two signals: TXD0 and RXD0.

General Purposes I/O (GPIO)
Calypso-Lite provides 16 GPIOs configurable in read or write mode by internal registers. In 56E30, we utilize 9 of them as follows , others are used in the dual function mode or N/A:

IO 0 : SPK_FM_HF

IO 1 : VOL_CLK

IO 2 : MELODY_INT

IO 3 : VOL_UpDown

IO 4 : FM_SPK

_IO 5 : X_

_IO 6 : ACCESSORY_IN_

_IO 7 : NRESET_OUT_

_IO 8 :_

_IO 9 : NLED_DRIVE_SD_

_IO 10 : FM_EN_

_IO 11 : FM_SCL_

_IO 12 : FM_SDA_

_IO 13 :_

_IO14_: SRAM high-byte enable

_IO15_: SRAM low-byte enable

Serial Port Interface (SPI)

The SPI is a full-duplex serial port configurable from 1 to 32 bits and provides 3 enable signals programmable either as positive or negative edge or level sensitive. This interface is working on 13MHz and is used for the GSM/GPRS baseband and voice A/D, D/A with IOTA

Memory Interface and internal Static RAM

For external memory device (Flash and SRAM), this interface performs read and write access with adaptation to the memory width. It also provides 6 chip-select signals corresponding each to an address range of 8 mega bytes. One of these chip-select is dedicated to the selection of an internal memory. In 56E30, we employ nCS0 (NROM_CS0) for external 64 Mbits Flash and nCS1 (NRAM_CS1) for external 16Mbits SRAM. A 2Mbit SRAM is embedded on the die and memory mapped on the chip-select nCS6 of the memory interface .The access cycle is guaranteed with 0 wait-state for any cycle frequency up to 39MHz. About others chip selects allocation are nCS2 (NDSCM_CS2) for DSC backend IC and nCS3 (NLCDM_CS3) for LCDM driver and nCS4 for melody IC ..

SIM Interface

The Subscriber Identity Module interface will be fully compliant with the GSM 11.11 and ISO/IEC 7816-3 standards. Its external interface is 3 Volts only. 5 Volts adaptation will be based on external level shifters.

JTAG

In 56E30, JTAG is used for software debugging.

Time Serial Port (TSP)

The TPU is a real-time sequencer dedicated to the monitoring of GSM/GPRS baseband processing. The TSP is a peripheral of the TPU which includes both a serial port (32 bits) and a parallel interface. The serial port can be programmed by the TPU with a time accuracy of the quarter of GSM bit. The serial port is uni-directional (transmit only) when used with IOTA. The serial port provides 4 enable signals programmable either as positive or negative edge or level sensitive. This serial port is derived from 6.5MHz and used to control the real time GSM windows for the baseband codec and the windows for ADC conversion.

TSP Parallel interface (ACT)

The parallel interface allows control 13 external individual outputs and 1 internal signal with a time accuracy of the quarter of GSM bit. These parallel signals are mainly used to control the RF activity. In 56F05, we employ 5 of them to control RF activity.

TSPACT1:   GSM_T/R
TSPACT2:   DCS_T/R
TSPACT3:   PCS_RX
TSPACT6:   TX_ON
TSPACT9:   Band Select
TSPACT10:   Latch enable

Radio Interface (RIF)

The RIF (Radio Interface) Module is a buffered serial port derived from the BSP peripheral module of the defined for TMS320C5X. The external serial data transmission is supported by a full-duplex double-buffered serial port interface. The interface is used for transfer of baseband transmit and receive data and also to access all internal programmation registers of the device.

Miscellaneous:

Some important Baseband /RF interface signals are defined as follows:
CLKTCXO: 13MHz VTCXO Clock from RF circuit
TCXOEN: 13MHz VTCXO Clock Enable signal

5.2 IOTA

Together with a digital base-band device (Calypso-Lite), IOTA is part of a TI DSP solution intended for digital cellular telephone applications including GSM 900, DCS 1800 and PCS 1900 standards (dual band capability).

It includes a complete set of base-band functions to perform the interface and processing of voice signals, base-band in-phase (I) and quadrature (Q) signals which support single-slot and multi-slot mode, associated auxiliary RF control features, supply voltage regulation, battery charging control and switch ON/OFF system analysis. IOTA interfaces with the digital base-band device through a set of digital interfaces dedicated to the main functions of Calypso-Lite, a base-band serial port (BSP) and a voice-band serial port (VSP) to communicate with the DSP core (LEAD), a micro-controller serial port to communicate with the micro-controller core and a time serial port (TSP) to communicate with the time processing unit (TPU) for real time control.

IOTA also includes on chip voltage reference, under voltage detection and power-on reset circuits.

Major functions of this chip are as follows:

Baseband Codec (BBC)

The baseband codec includes a two-channel uplink path and a two-channel downlink path.

The baseband uplink path (BUL) modulates the bursts of data coming from the DSP via the baseband serial port (BSP) and to be transmitted at the antenna. Modulation is performed by a GMSK modulator. The GMSK modulator implemented in digital technique generates In-phase (I) and Quadrature (Q) components, which are converted into analog base-band by two 10 bits DACs filters. It also includes secondary functions such as DC offset calibration and I/Q gain unbalance.

The baseband downlink path (BDL) converts the baseband analog I & Q components coming from the RF receiver into digital samples and filters these resulting signals through a digital FIR to isolate the desired data from the adjacent channels. During reception of burst I & Q digital data are sent to the DSP via the baseband serial port (BSP) at a rate of 270 KHz.

Automatic Frequency control (AFC)

The automatic frequency control function consists of a digital to analog converter optimized for high resolution DC conversion. Its purpose is to control the frequency of the GSM 13MHz oscillator to maintain mobile synchronization on the base station and allow proper transmission and demodulation.

Automatic Power Control (APC)

Purpose of the Automatic Power Control (APC) is to generate an envelope signal to control the power ramping up, ramping down and power level of the radio burst.

The APC structure is intended to support single slot and multi-slots transmission with smooth power transition when consecutive bursts are transmitted at different power level. It includes a DAC and a RAM in which the shape of the edges (ramp-up and ramp-down) of the envelope signals are stored digitally. This envelope signal is converted to analog by a 10 bits digital to analog converter. Timing of the APC is generated internally and depends of the real time signals coming from the TSP and the content of two registers which control the relative position of the envelope signal versus the modulated I & Q.

Time serial port (TSP)

Purpose of the time serial port is to control in real time the radio activation windows of IOTA which are BUL power-on, BUL calibration, BUL transmit, BDL power-on, BDL calibration and BDL receive and the ADC conversion start.

These real time control signals are processed by the TPU of DBB and transmitted serially to ABB via the TSP, which consists in a very simple two pins serial port. One pin is an enable (TEN) the other one the data receive (TDR). The master clock CK13M divided by 2 (6.5MHz) is used as clock for this serial port.

Voice band Codec (VBC)

The VBC processes analog audio components in the uplink path and transmits this signal to DSP speech coder through the voice serial port (VSP). In the downlink path the VBC converts the digital samples of speech data received from the DSP via the voice serial port into analog audio signal. Additional functions such as programmable gain, volume control and side-tone are performed into the voice band codec.

Micro-controller serial port (USP)

The micro-controller serial port is a standard synchronous serial port. It consists in three terminals, data transmit (UDX), data receive (UDR) and port enable (UEN). The clock signal is 13MHz clock. The USP receives and sends data in serial mode from and to the external micro-controller and in parallel mode from and to the internal GSM Baseband a Voice A/D D/A modules. The micro-controller serial port allow read and write access of all internal registers under the arbitration of the internal bus controller.

SIM card shifters (SIMS)

The SIM card digital interface in ABB insures the translation of logic levels between DBB and SIM card, for transmission of 3 different signals; a clock derived from a clock elaborated in DBB, to the SIM card (DBBSCK➔SIMCLK). a reset signal from DBB to the SIM card (DBBSRST➔SIMRST), and serial data from DBB to SIM card (DBBSIO➔SIMIO) and vice-vera.

The SIM card interface can be programmed to drive a 1.8V and 3 V SIM card

Voltage Regulation (VREG)

Linear regulation is performed by several low dropout (LDO) regulators to supply analog and digital baseband circuits.

(1) LDO **VRDBB** generates the supply voltage (1.85V, 1.5V,and 1.35V) for the digital core of DBB. In 56E30, it is programmed to 1.5V. This regulator takes power from the battery voltage
(2) LDO **VRABB** generates the supply voltage 2.8V for the analog function of ABB. It is supplied by the battery.
(3) LDO **VRIO** generates the supply voltage 2.8V for the digital core of ABB and digital I/O's of DBB and ABB. It is supplied from battery voltage.
(4) LDO **VRMEM** generates the supply voltages 2.8V for DBB memory interfaces I/O's.
(5) LDO **VRRAM** generates the supply voltages 2.8V for DBB memory interfaces I/O's
(6) LDO **VRRTC** generates the supply voltages (1.85,1.5, or 1.35V) and supply voltage 1.5V for the following block of DBB (real time clock and 32K oscillator). It's supplied by UPR
(7) LDO **VRSIM** generates the supply voltages (1.8V, 2.9V) for SIM card interface I/O's

Baseband Serial Port (BSP)

The BSP serial interface is used for both configuration of the GSM baseband and voice A/D D/A (read and write operation in the internal registers), and transmission of the radio data to the DSP during reception of a burst by the downlink part of the GSM baseband & voice A/D D/A. Four pins are used by the serial port: BFSR and BDR for receive, BFSX and BDX for transmit. BDX is the transmitted serial data output. BFSX is the transmit frame synchronization and is used to initiate the transfer of the transmit data. BDR is the received serial input. BFSR is the receive frame synchronization and is used to initiate the reception data.

Battery charger Interface (BCI)

The main function of the ABB charger interface is the charging control of either a 1-cell Li-ion Battery or 3-serie Ni-MH cell batteries with the support of the micro-controller. The battery monitoring uses the 10 bit ADC converter from the MADC to measure the battery voltage, battery temperature, battery type, battery charge current, battery charger input voltage. The magnitude of the charging current is set by the 10 bits of a programming register converted by an 10 bit Digital to Analog Converter, whose output sets the reference input of the charging current control loop. The battery charger interface performs also some auxiliary functions. They are battery pre-charge, battery trickle charge and back-up battery charge if it is rechargeable.

Monitoring ADC (MADC)

The MADC consists in a 10-bit analog to digital converter combined with a nine inputs analog multiplexer. Out of the nine inputs five are available externally, the four remaining being dedicated to main battery voltage, back up battery voltage, charger voltage and charger current monitoring. On the five available externally three are standard inputs intended for battery temperature, battery type measurements.

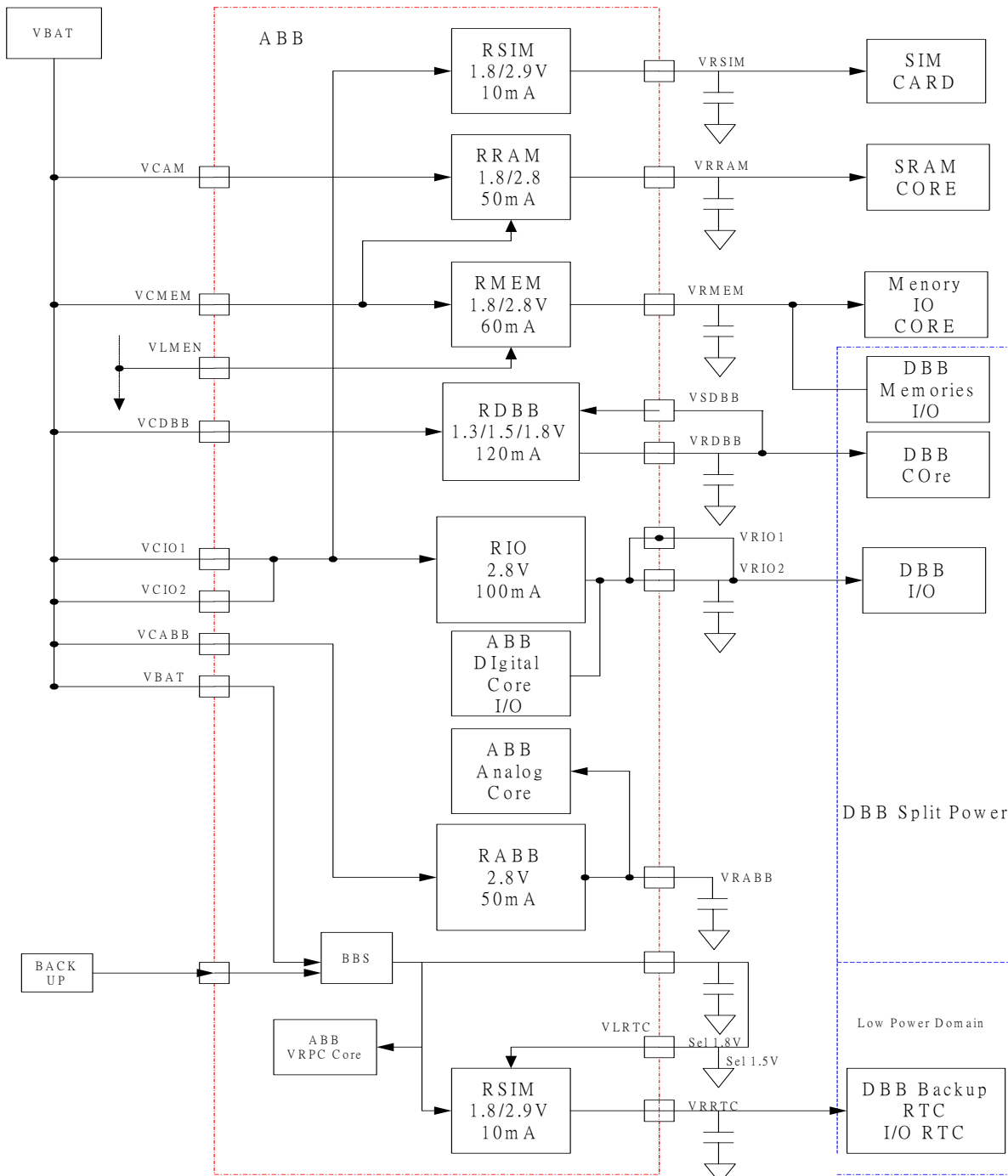### Reference Voltage / Power on Control (VRPC)

An integrated band-gap generates a reference voltage. This reference is available on an external pin for external filtering purpose only. This filtered reference is internally used for analog functions. The external resistor connected between pin IBIAS and GNDREF sets, from the band-gap voltage, the value of the bias currents of the analog functions. The VRPC block is in charge to control the Power ON, Power OFF, Switch On, and Switch OFF sequences. Even in Switch OFF state some blocks functions are performed. These "permanent" functions are functions, which insure the wake-up of the mobile such as ON/OFF button detection or charger detection. Interrupts are generated at power-down detection of the PWON button and when abnormal voltage conditions are detected.

Internal bus and interrupt controller (IBIC)

Read and write access to all internal registers being possible via both the BSP and USP, purpose of the internal bus controller is to arbitrate the access on the internal bus and to direct the read data to the proper serial port. During reception of a burst the internal bus controller assign the transmit part of the BSP to the base-band downlink to transfer the I & Q samples to the DSP.

This block also handles the internal interrupts generated by the MADC, BCI and VRPC blocks and generates the micro-controller interrupt signal INT2.

5.3 Power Supply

Description:

The voltage regulators embedded in IOTA consists of seven sub blocks. Several low-dropout (LDO) regulators perform linear voltage regulation. These regulators supply power to internal analog and digital circuit, to DBB processor, and to external memory.

· LDO (**VRDBB**) is a programmable regulator that generates the supply voltages(1.8V,1.5V and 1.3V) for the core of the DBB processor. The main battery supplies VRDBB.

· LDO (**VRIO**) generate the supply voltage (2.8V) for the digital core and I/O of the TWL3014 device. The main battery supplies VRIO.

· LDO (**VRMEM**) is a programmable regulator that generates the supply voltages (2.8V and 1.8V) for external memories (typically flash memories) and DBB memory interface I/O. The main battery supplies VRMEM.

· LDO (**VRRAM**) is a programmable regulator that generate the supply voltages (2.8V and 1.8V) the external memory (typically SRAM memories) and DBB memory interface I/Os. The main battery supplies VRRAM.

· LDO (**VRABB**) generates the supply voltage (2.8V) for the analog functions of the TWL 3014 devices. The main battery supplies VRABB.

· LDO (**VRSIM**) is a programmable regulator that generates the supply voltages (2.9V and 1.8V) SIM card and SIM card devices. The main battery supplies VRSIM.

· LDO (**VRTC**) is a programmable regulator that generate the supply voltage (1.8V.1.5Vand 1.3V) for real time clock and the 32-KHZ oscillator located in the DBB device during all modes. The main or backup battery supplies VRTC.

5.3.1 System power on/off Sequence

Power on mode

On the plug-in of the valid main battery or backup battery, an internal reset is generated (POR).
After a power-on sequence, the TWL3014 device is in the BACKUP or OFF state.

When these conditions occur in the power on state, the hardware power on sequence starts:

1. Enable band-gap (VREF and IREF)
2. Check if Main Battery voltage is greater than 3.2V
3. Enable charge VRDBB-VRABB-VRMEM-VRRAM
4. Regulator OK.
5. ON_nOFF=1, ABB RSTz=1
6. NRESET pin is set from 'L' to 'H'
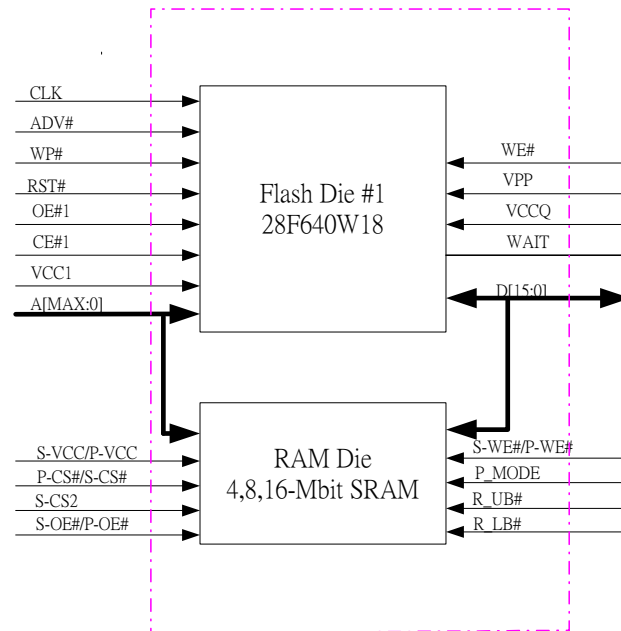7. 13MHz clock oscillator is enabled

Power off mode

This state is reached when there is not enough voltage in the main battery and backup battery or when both batteries are disconnected.

1. Send INT1
2. Start 5*T watchdog Timer , T= 32K period
3. ON_nOFF=0
4. ABB RSTz=0
5. Disable the LDO's using MSKOFF content and the band-gap
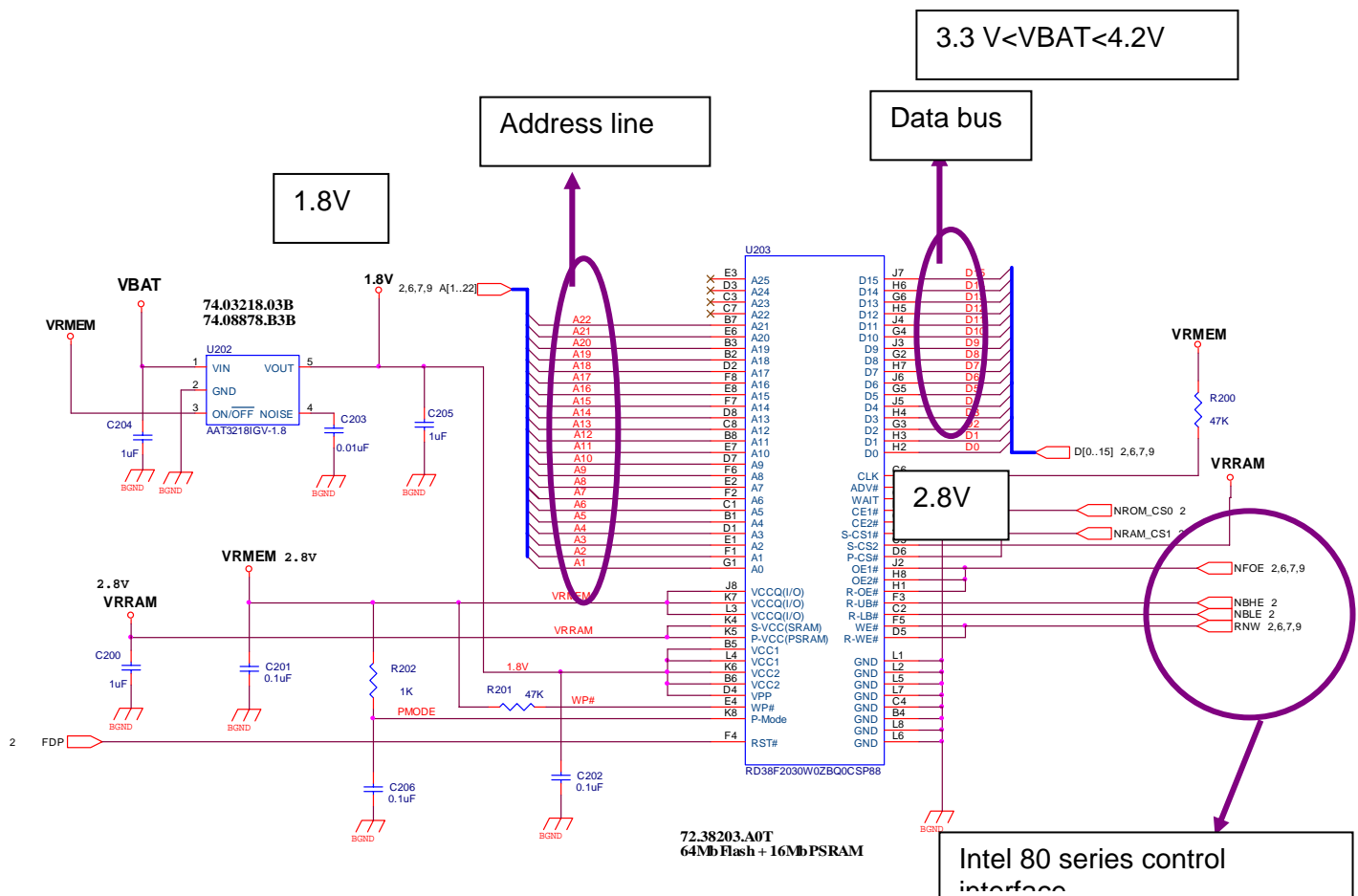6. "MBATLOW"=0

5.4 Memory circuit

Block diagram

```
                        ┌─ · ─ · ─ · ─ · ─ · ─ · ─ · ─ · ─┐
        CLK             │   ┌──────────────────┐          │
        ADV#            │   │                  │          │
        WP#             │   │                  │   WE#    │
        RST#            │   │   Flash Die #1   │   VPP    │
        OE#1            │   │   28F640W18      │   VCCQ   │
        CE#1            │   │                  │   WAIT   │
        VCC1            │   │                  │          │
        A[MAX:0]        │   │                  │  D[15:0] │
                        │   └──────────────────┘          │
                        │                                  │
                        │   ┌──────────────────┐          │
        S-VCC/P-VCC     │   │                  │ S-WE#/P-WE# │
        P-CS#/S-CS#     │   │   RAM Die        │  P_MODE  │
        S-CS2           │   │   4,8,16-Mbit SRAM│ R_UB#   │
        S-OE#/P-OE#     │   │                  │  R_LB#   │
                        │   └──────────────────┘          │
                        └─ · ─ · ─ · ─ · ─ · ─ · ─ · ─ · ─┘
```
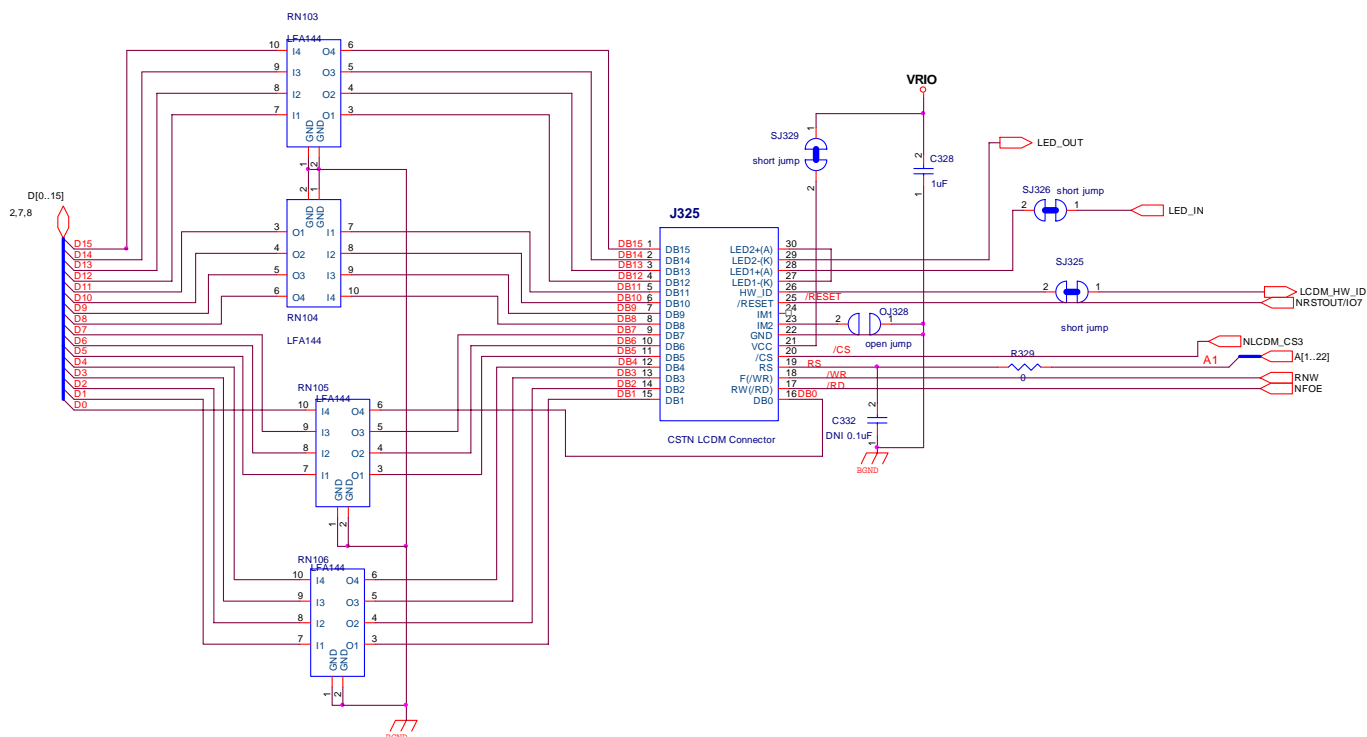
Description:

The two diagrams show the memory circuit of 56F05 and internal package connections for the Stacked CSP family with multiple die. The 64-Mbit 1.8 Volt Intel Wireless Flash Memory Stacked CSP Family encompass multiple flash memory + 16M bit RAM die combinations.
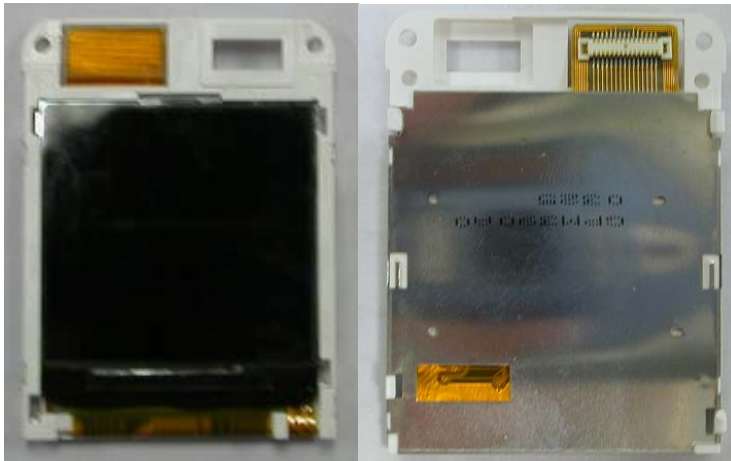
BenQ *mobile*

Schematic

3.3 V<VBAT<4.2V

Address line

Data bus

1.8V

2.8V

Intel 80 series control interface

VBAT

VRMEM

74.03218.03B
74.08878.B3B

U202

1.8V 2,6,7,9 A[1..22]

VRMEM

R200 47K

VRRAM

U203

RD38F2030W0ZBQ0CSP88

72.38203.A0T
64Mb Flash + 16Mb PSRAM

NROM_CS0 2
NRAM_CS1 1
NFOE 2,6,7,9
NBHE 2
NBLE 2
RNW 2,6,7,9

D[0..15] 2,6,7,9

5.5 LCD module (LCDM)

Connector between PCBA and LCDM

LCDM_HW_ID (ADIN1) voltage allocation vs LCDM vendor : (we use the ADIN1 (Iota) to detect the LCDM vendor)

```
272,        /* LCDM_Nanya       : 0.0 ~ 0.272V */
410,        /* Reserve          : 0.273 ~ 0.410V */
616,        /* Reserve          : 0.411 ~ 0.616V */
926,        /* Reserve          : 0.617 ~ 0.926V */
1390,       /* LCDM_GiantPlus   : 0.927 ~ 1.390V */
1718,       /* Reserve          : 1.391 ~ 1.718V */
```
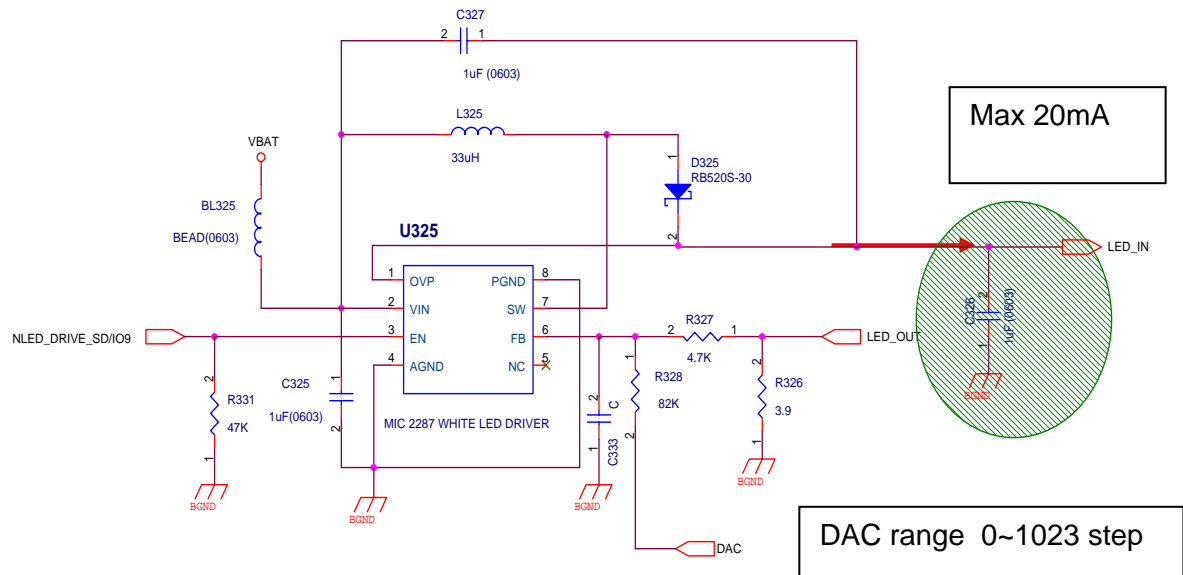
LCM mechanical outline

Description

This display module is a transmissive color STN (CSTN) Liquid crystal display (LCD) module of glass construction with a black background. The display has an internal transflector. The display consists of 128 (xRGB Stripe) x 128 pixel with 65K colors. bar connections to a flex foil accommodating components to drivers and the backlighting system. The backlighting system will consist of one light guide illumination both cells with a white backlight. Interconnection to the main board will be by a board to board connector.
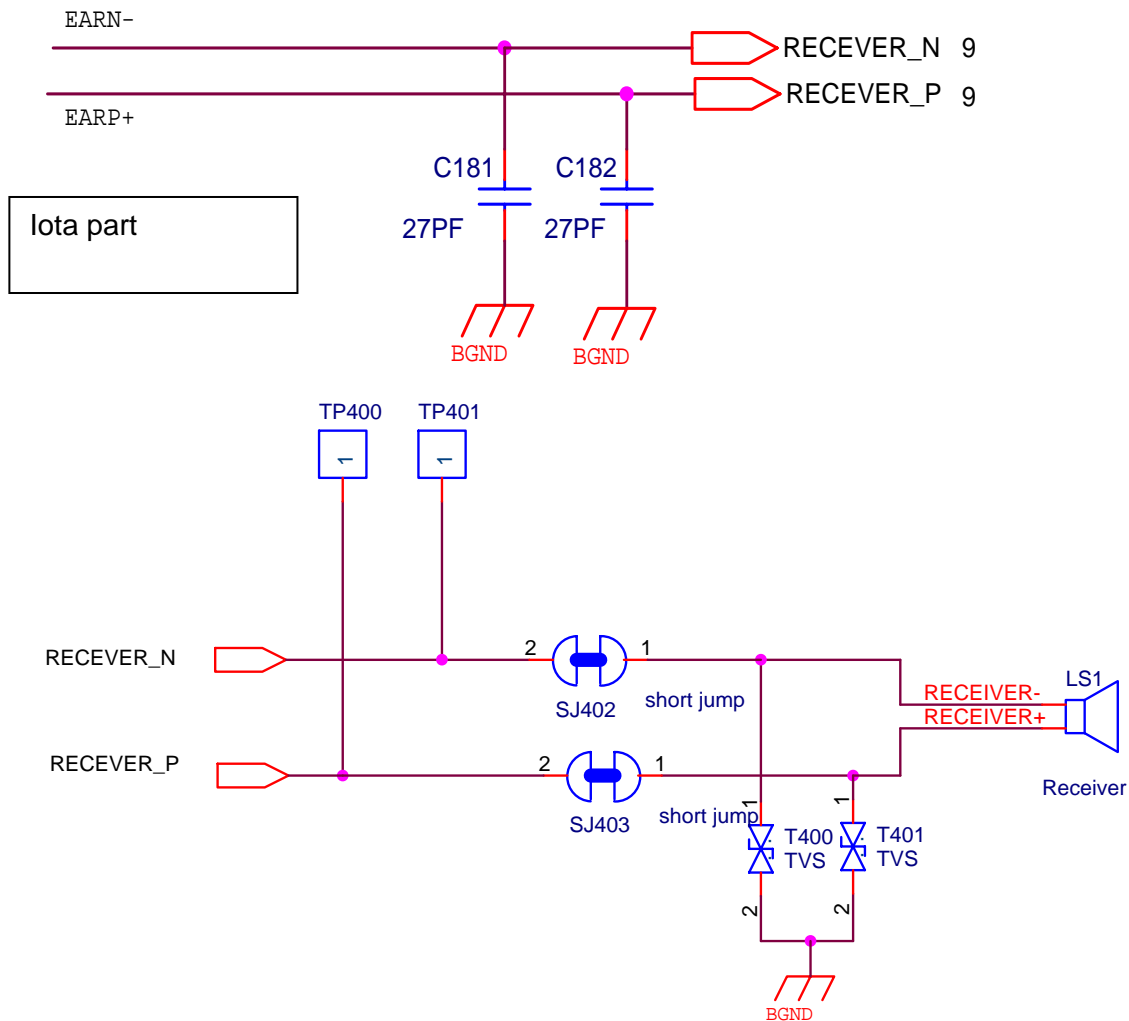
This display module consists of:

◆ CSTN Cell with polarizers, COG

◆ Enhancement films (DBEF + 2*BREF)

◆ Mechanical support/carrier system with Magnesium frame

◆ One illumination system with 2 White LED's.

◆ Flexfoil with SMD component (include board to board connector for connection to the main part of the phone and between the module)

BenQ *mobile*

White LED driver schematic

Max 20mA

DAC range 0~1023 step

6 Interfaces

6.1 Audio circuit

3.7.1 Uplink path

Downlink path

Description

The audio circuit is divided into two parts, uplink and downlink path.

For uplink path, the analog voice signals are fed into IOTA from the microphone differential input and then transmitted to G2 DSP via the voice-band series port (VSP). After being modulated, the signals go through the uplink I/Q path to the RF transceiver and transmitted from the antenna.

The microphone circuit is biased from MICBIAS of IOTA. The bias circuit, R163, R164, R162 mainly provides the optimal operation point for the microphone signals, MICP and MICN. For downlink path, the signals received from the antenna are down-converted to I/Q signals and then transmitted to G2 DSP. After being demodulated, the signals are fed to IOTA via voice-band interface and then amplified to drive the receiver in the EARP and EARN .

BenQ *mobile*

6.2 Melody IC

Schematic

Yamaha 16 tone melody IC

Gain = R404 / R403
f1 = 1 / (2pi * R403 * C404)
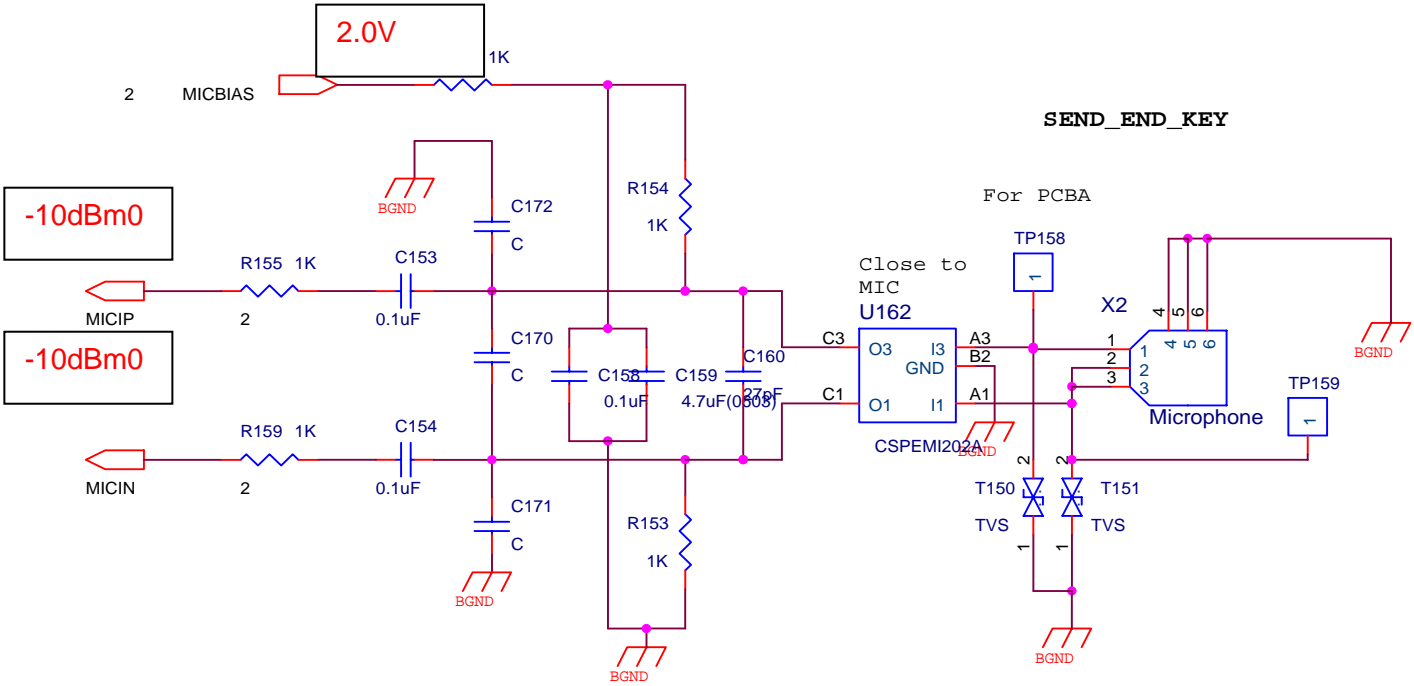f2 = 1 / (2pi * R404 * C407)

Description:

The Yamaha Melody IC (YMU759 MA2) mainly generate multi-tone for speaker. The main features are

1. Equipped with FM generator function and ADPCM playback function
3. Number of voice simultaneously generated
4. When only 2-operator tone are used : up to 16 voices can be generated simultaneously
5. When only 4-operator tone are used : up to 8 voices can be generated simultaneously
6. Built-in 4-bit 1ch ADPCM decoder, and supports two kinds of sampling frequency , 4kHz and 8kHz.
7. Built-in output 550mW (AVDD=3.6V) speaker amplifier
8. Built-in hardware sequencer
9. Built-in circuit for sound quality correcting equalizer
10. Supports stereophonic D/A converter
11. Provided with a stereophonic analog output terminal for headphone
12. 4 wire serial interface or 12 wire parallel interface can be selected
13. PLL is built-in to support master clock in 2MHz to 20MHz range
14. Support power down mode(Typical current: 1uA or less)
15. Power supply is divided into analog power supply for speaker amplifier and power supply for the others
    Analog power supply for speaker amplifer (SPVDD): 2.7V~4.5V (Typ 3.6V)
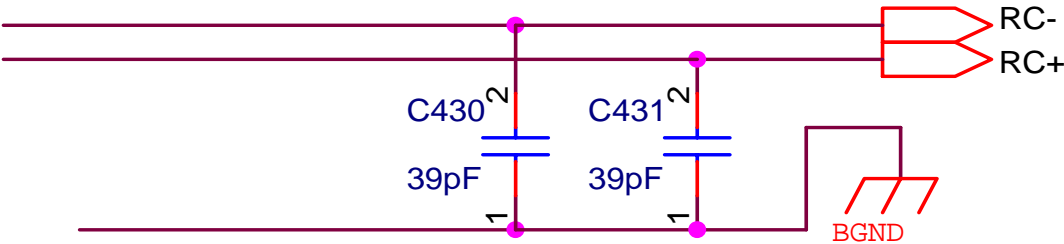   Digital power supply for the others (VDD):2.7V~3.3V(Typ 3.0V)

Besides, IO4 control analog switch U401 to decide FM output to headset or Loud speaker.
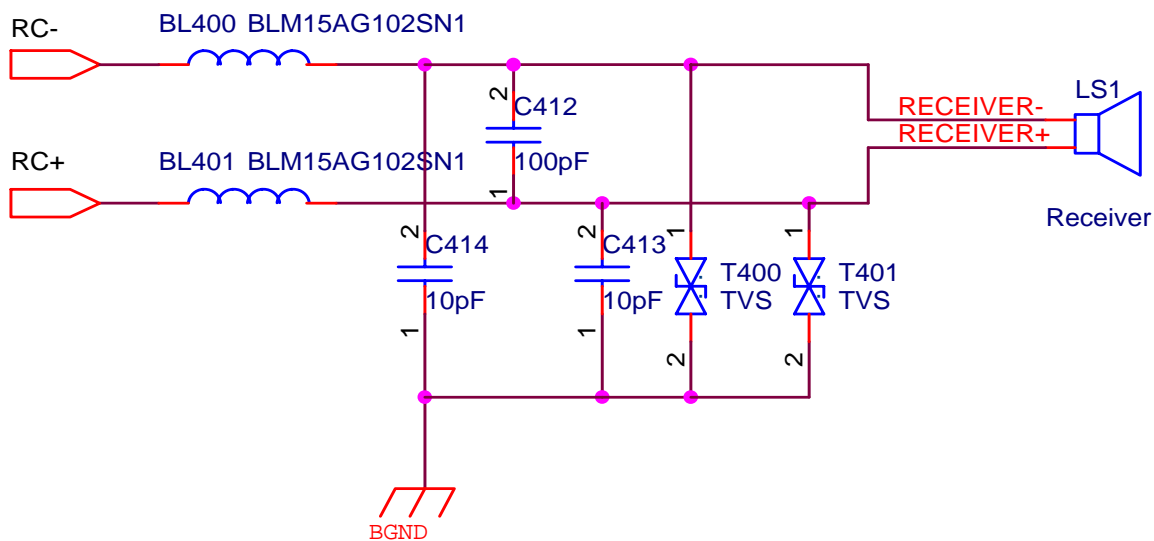
6.3   Audio circuit

Uplink path
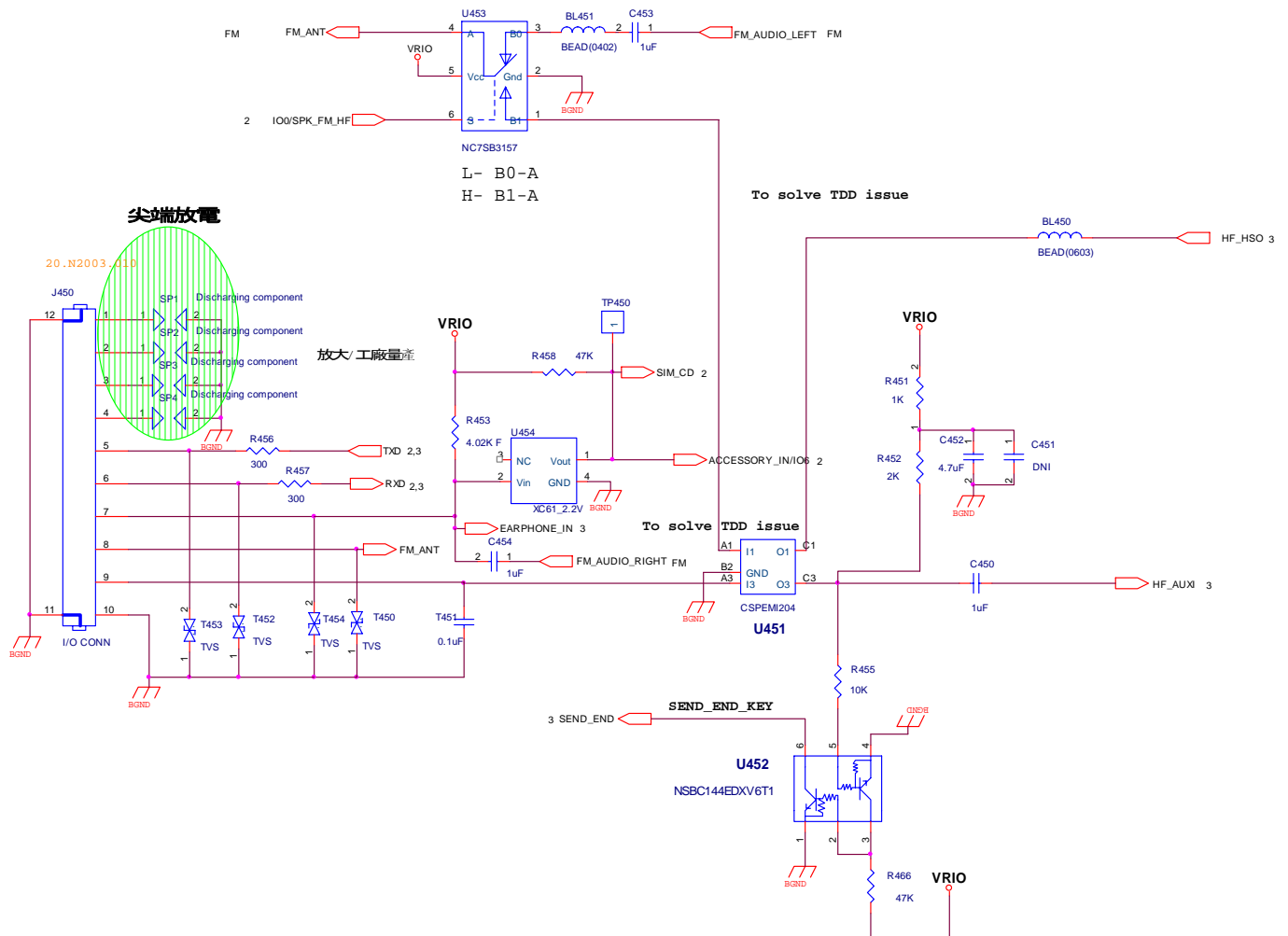

Downlink path

Iota part

Description

The audio circuit is divided into two parts, uplink and downlink path.

For uplink path, the analog voice signals are fed into IOTA from the microphone differential input and then transmitted to G2 DSP via the voice-band series port (VSP). After being modulated, the signals go through the uplink I/Q path to the RF transceiver and transmitted from the antenna.
The microphone circuit is biased from MICBIAS of IOTA. The bias circuit provides the optimal operation point for the microphone signals, MICP and MICN. For downlink path, the signals received from the antenna are down-converted to I/Q signals and then transmitted to G2 DSP. After being demodulated, the signals are fed to IOTA via voice-band interface and then amplified to drive the receiver in the EARP and EARN.

6.4 10 Pins I/O connector

Schematic

Accessory type table :

0.8V < ADIN3 < 1.3V Define : Handsfree
0.45V < ADIN3 < 0.65V Define : DataCable

Description

The 10 Pins I/O connector circuit is used either for the headsfree or the data service. The SIM_CD will be pulled to low level when headsfree or data cable is plugged-in.

And the SEND_END_KEY function is that when handsfree work , user can send the call or end the call in the handsfree push bottom key. This function use the Keypad interrupt (G2-Lite) to generate the send-end function.
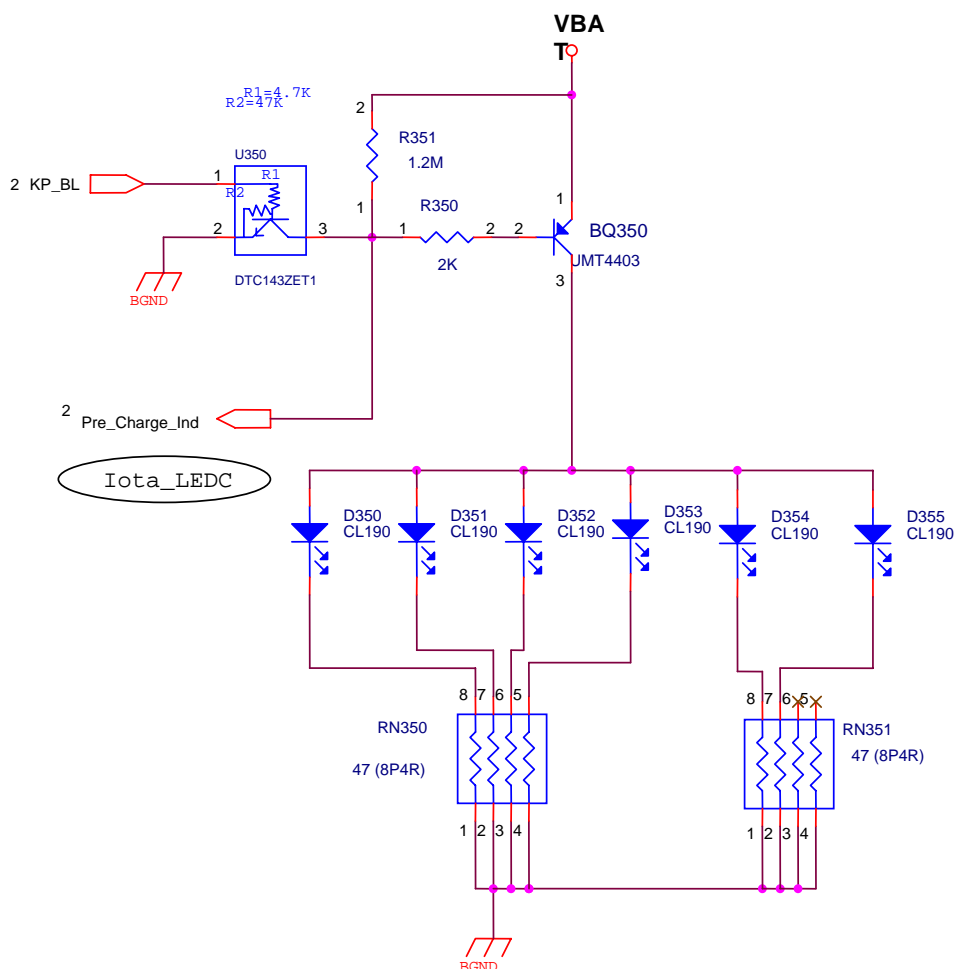
The HF_HSO is the handsfree speaker output and the HF_AUXI is the handsfree Micphone input for the Iota.

The EARPHONE _IN is connected to the Iota ADIN3 to judge accessory type (refer to the Accessory type table)

The IO0 control analog switch U453 to decide FM(L) or speech(H) output to headset.
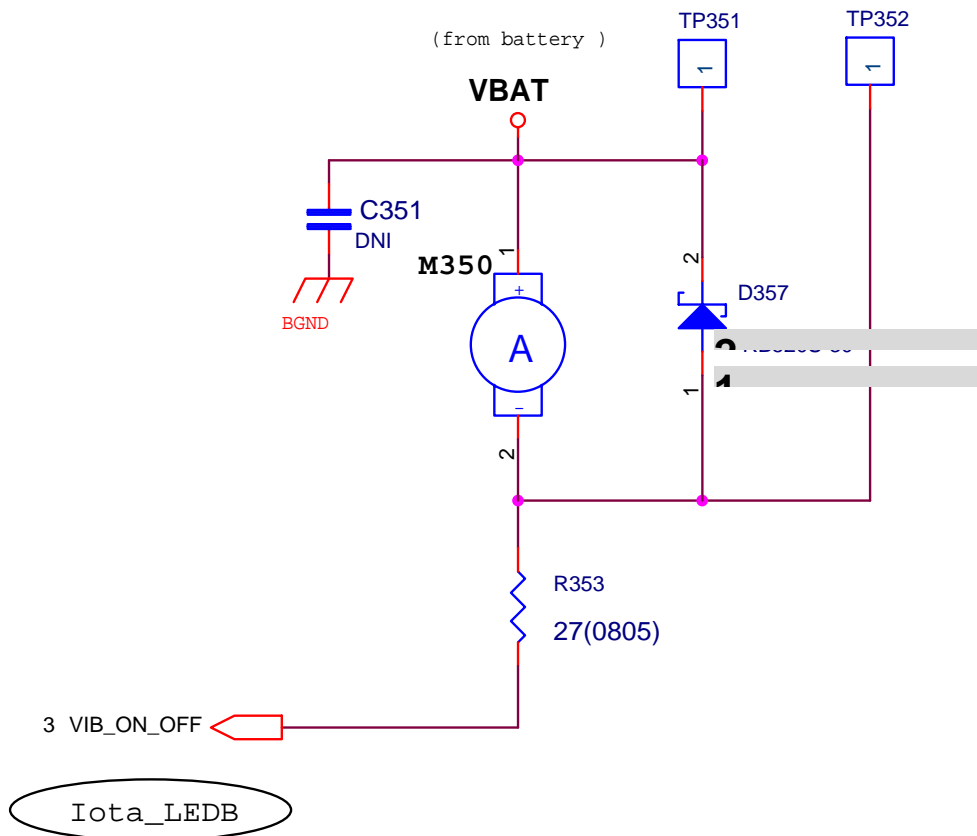
6.5 Keypad LED circuit

Schematic

Description

M315 employs six blue LEDs for keypad backlight and pre-charging indicator. The ON_OFF timing of (D350, D351, D352, D353, D354, D355) are controlled by U350 according to KP_BL = H (ON) /L (OFF). Under the default condition (VBAT=3.8V), the average current of one keypad backlight LED is about 6.25mA. So total current through LEDs is 40mA. If VBAT < 3.2V , as charger plug in handset ,Iota will do the pre-charging function and LEDC will L(ON) then these six LEDs will be turn on.

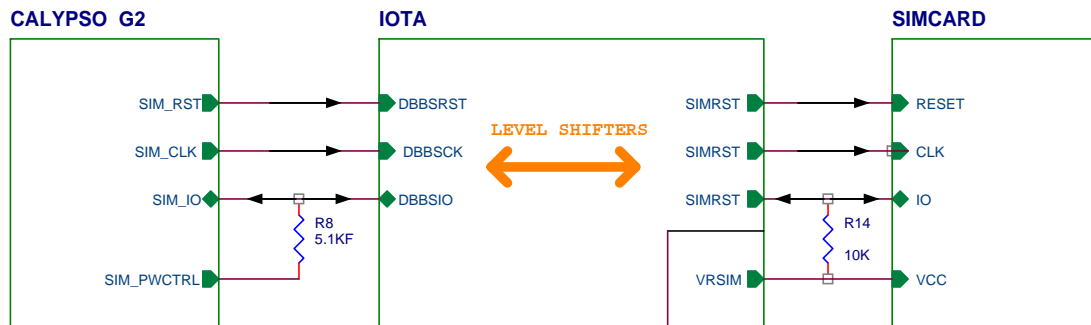## 6.6 Vibrator

Schematic

Description

Vibrator is enabled by LEDB control logic in IOTA. When the logic is set to 'H', the motor will activate. R353 are used to control operating current and D1 is used to reduce EMF. Under the condition of VBAT = 3.8V, the average drain current is around 66.5mA.

6.7   SIM Circuit

Schematic

Description

The SIM interface of IOTA is composed by a dedicated LDO and I/O level shifters. It supports 3V and 1.8V SIM cards (In 56E30 just use the 3V).

SIM_IO(I/O):   Data
SIM_RST(O): Reset signal
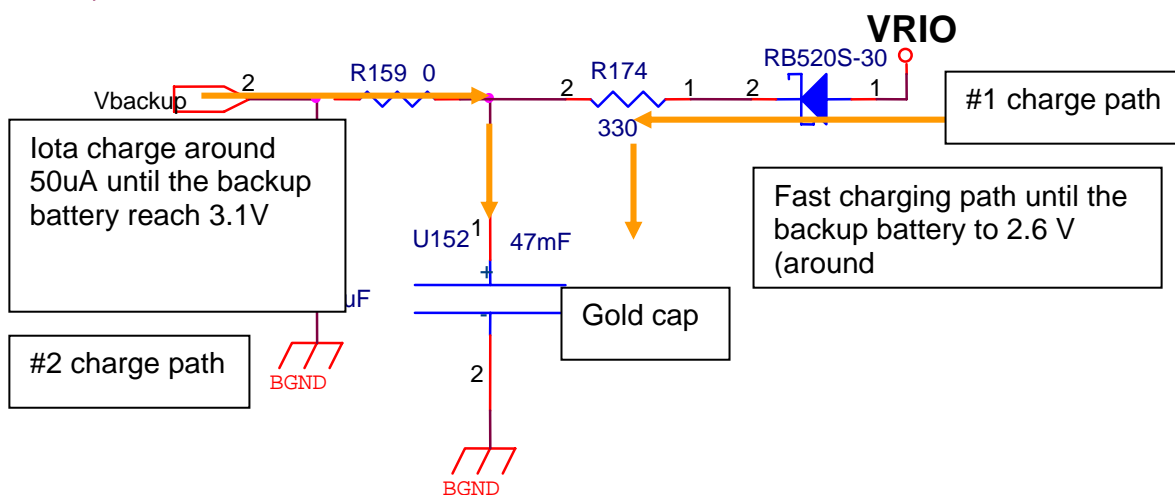**SIM_CLK(O): Clock (1.6MHz/3.2MHz)**
The SIM card digital interface insures the translation of logic levels between CALYPSO-Lite and SIM card. Selection of pull-up resistor is trade-off between the SIM IO rising time and current consumption

Technical Documentation

6.8 Keypad

Schematics

Description

1. The keypad is made of a 5 Column x 5 Row matrixes.
2. The keypad matrix is as follows:

Function		COL0	COL1	COL2	COL3	COL4	ROW0	ROW1	ROW2	ROW3	ROW4
END/PWR	S371										
3	S350	0					0				
2	S351	0						0			
1	S352	0							0		
DOWN	S353	0								0	
MENU	S354	0									0
6	S355		0				0				
5	S356		0					0			
4	S357		0						0		
LEFT	S358		0							0	
YES/Send	S359		0								0
8	S361			0				0			
7	S362			0					0		
UP	S363			0						0	
SEND	S364			0							0
9	S360			0			0				
#	S365				0		0				
0	S366				0			0			
*	S367				0				0		
RIGHT	S368				0					0	
NO	S369				0						0

6.9 RTC Circuit

Schematic

VRIO

Vbackup 2 — R159 0 — 2 R174 1 — 2 RB520S-30 1 — #1 charge path

330

Iota charge around 50uA until the backup battery reach 3.1V

U152 1 47mF

Fast charging path until the backup battery to 2.6 V (around

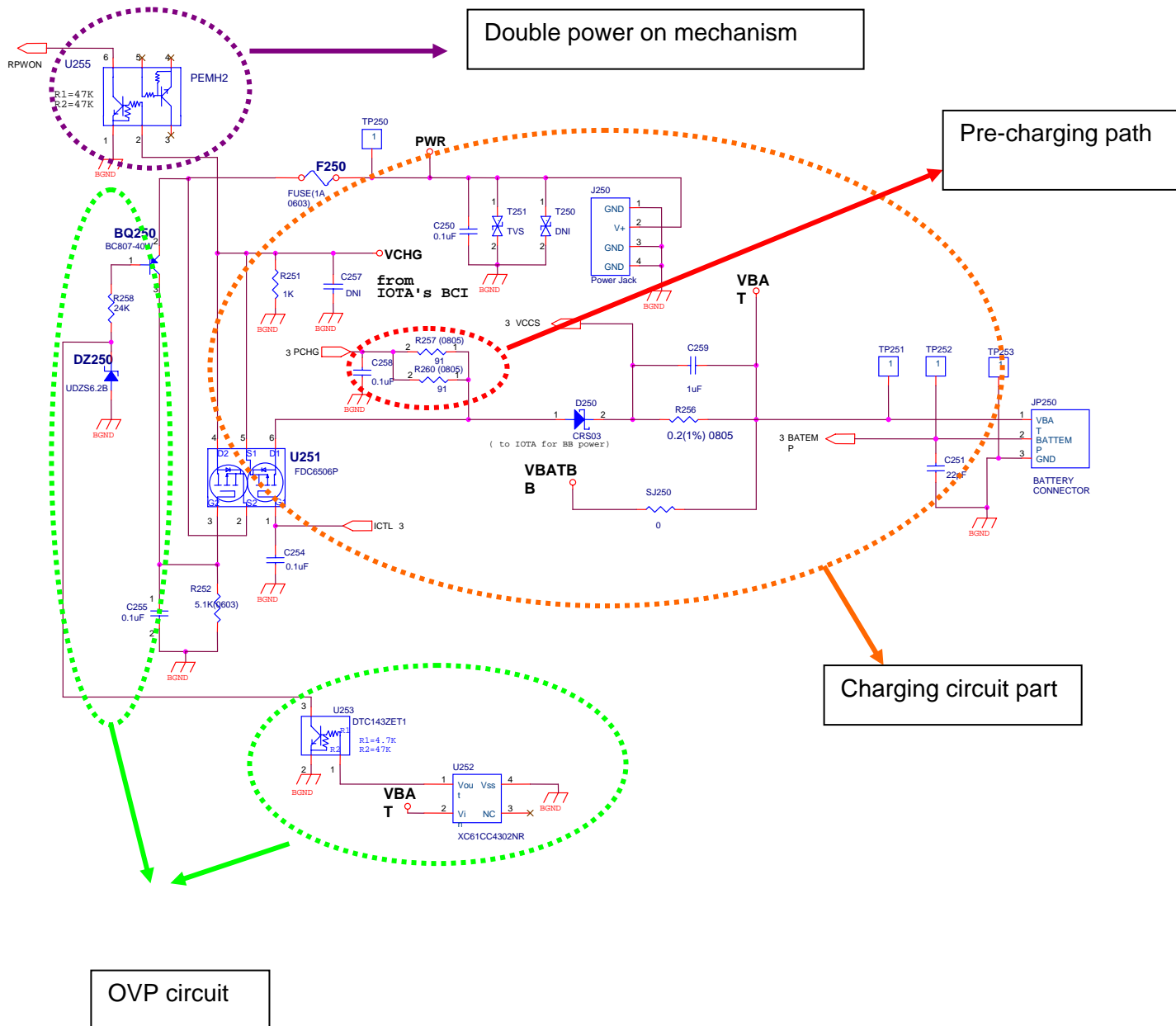#2 charge path

Gold cap

BGND

2

BGND

Description

Gold cap is employed as backup battery. When main battery is removed or battery voltage is lower than backup battery voltage, backup battery will supply real-time clock and the 32.768Hz oscillator. The supply current for backup battery is about 50uA. There are two charging paths for backup battery. The charge path #1 charge backup battery until backup battery voltage reachs around 2.6V. The charge path #2 is always on until backup battery is full-charged

7 Charging circuit

Schematic

Double power on mechanism

Pre-charging path

Charging circuit part

OVP circuit

Description

This circuit mainly contains OVP, Charge circuit part , and Double power on mechanism . The OVP gives system a voltage protection of over charger voltage or battery over charged. If the charger voltage is over 6.8 V and the battery is over charged to 4.4 V the OVP mechanism will work.

F250 is a 1A fuse to assure charging current under 1A limit. The group of BQ250 and DZ250 compose the charger over-charge protection circuit. The cut-off voltage is 6.8V. While the charger voltage is over 6.8V, the circuit will turn off U251 PMOS to stop charge process. The group of 253, BQ250 and U252 compose the battery over-charge protection circuit. While the battery voltage is over 4.4V, the circuit will turn on U252 to turn off U251 PMOS to stop charge process.

The normal charging operation theory (battery voltage above 3.2V) is that IOTA monitors charger voltage via VCHG pin to decide whether charger plug in or out, and control power P-MOSFET (U251.1) via ICTL pin. If phone enters into charging mode, the ICTL pin will limit the maximum charging current at 750mA(max) by sensor the R256 and control CC_H / CV mode. When VBAT equals to 4.2V, Iota will stop the charge function . The charging current will decrease until the charging current is lower than 30mA. In charging process, IOTA BCI always monitor the charging status. It can monitor charging current by current sense resistor (R256), VBAT and temperature by ADC pin, and charging time by internal timer. If there is any abnormal status happened while charging, IOTA BCI will turn off power P-MOSFET (U251.1) via ICTL pin to prevent any hazardous condition happening.

When VBAT<3.2V, charging state enters in "pre-charge" state. In this state, U251 is off and IOTA will supply pre-charge current from VCHG through VBAT to charge battery. We use R257 and R260 to set the pre-charge current between 35mA(VBAT=3V) to 75mA(VBAT=2V).

Double power on mechanism, this mechanism is to avoid the VCHG > Vbat power on function fail , therefore we use the Remote power on function to double turn on the power on sequence.